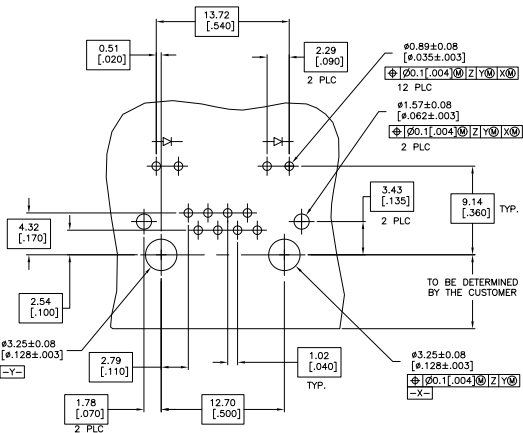
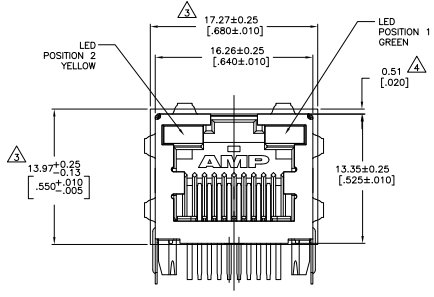
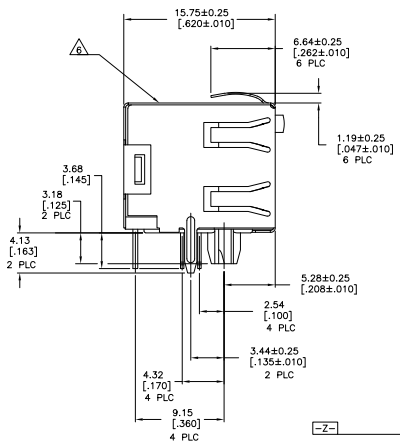


REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00	REVISIONS			
B1	08-013486				



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

- MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
- TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [0.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.000050] MINIMUM THICK NICKEL.
- SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.000050] MINIMUM SATIN NICKEL WITH 2.03µm[0.00080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
- LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS - 8.89µm[0.00350] THICK Sn/Cu OVER 2.03µm[0.00080] THICK Ag OVER 1.02µm[0.00040] THICK Cu OVER 3.56µm[0.00140] THICK Ni OVER 1.02µm[0.00040] THICK Cu UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- MANUFACTURING DATE CODE: LOCATED APPROX. AS SHOWN. FIRST 2 DIGITS = LAST 2 DIGITS OF YEAR. NEXT 2 DIGITS = MANUFACTURING WORK WEEK. LAST DIGIT = DAY OF WEEK WITH SUNDAY = 1.

AS SHOWN	1761750-1
DESCRIPTION	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REVISED BY	DATE	REVISED BY	DATE
DESIGNED BY	APPROVED BY	DESIGNED BY	DATE	DESIGNED BY	DATE
DATE	DATE	DATE	DATE	DATE	DATE
108-1163-4	114-2154	108-1163-4	114-2154	108-1163-4	114-2154
108-1163-4	114-2154	108-1163-4	114-2154	108-1163-4	114-2154
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